

**Objective:** The primary objective of this course is to provide students with hands-on exercises of the different features of Autodesk Moldflow Insight Premium and Ultimate (Compression Molding) for Thermoset materials related to microchip encapsulation molding processes.

**Level:**  
Advanced

**Duration:** 1 day  
(8 hrs.)

**Who Should Attend:** This course is designed for any intermediate Autodesk Moldflow Insight Premium and Ultimate (Compression Molding) user who will be performing microchip encapsulation molding analysis projects.

**Pre-requisites:** Before attending this course, students must attend the courses titled *Autodesk Moldflow Insight Fundamentals* and *Reactive Molding with Autodesk Moldflow Insight*.

# Microchip Encapsulation with Autodesk® Moldflow® Insight

## Autodesk® Official Training



### Course Description

In this course, students learn features, functionalities and workflows in Autodesk Moldflow Insight Premium through hands-on exercises related to microchip encapsulation molding processes used for thermoset materials.

### Course Outline – Microchip Encapsulation with Autodesk Moldflow Insight

- **Microchip Encapsulation Molding Overview:** Overview of microchip encapsulation molding definitions and applications
- **Microchip Encapsulation Molding Analysis Steps:** Overview of the steps required to set up microchip encapsulation molding analyses
- **Modeling and Mesh Requirements for Microchip Encapsulation Analysis:** Discusses what can be modeled for microchip encapsulation molding analysis. Discusses how the mesh quality influences the analysis of microchips
- **Process Settings for Microchip Encapsulation Molding:** Discusses in detail all the advanced options used to run a microchip encapsulation molding analysis. Covers all 3D solvers, Midplane and Dual Domain capabilities
- **Results Interpretation and Customization for Microchip Encapsulation Molding:** Discusses results manipulation and general interpretation. Practice concentrating on display methods for each type of mesh
- **Compression Molding with Wire Sweep:** Workflow required to set up a compression molding of a microchip encapsulated part with wire sweep and look at the results

**For a quote,** please download and complete the quote form from [www.a-zssolutions.com](http://www.a-zssolutions.com) and email us at: [info@a-zssolutions.com](mailto:info@a-zssolutions.com) or fax it to +1-404-996-1187